# **MOSFET** – N-Channel, SUPREMOS, FRFET

600 V, 48.5 A, 65 m $\Omega$ 

# FCH47N60NF

## Description

The SUPREMOS<sup>®</sup> MOSFET is ON Semiconductor's next generation of high voltage super-junction (SJ) technology employing a deep trench filling process that differentiates it from the conventional SJ MOSFETs. This advanced technology and precise process control provides lowest Rsp on-resistance, superior switching performance and ruggedness. SUPREMOS MOSFET is suitable for high frequency switching power converter applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications. SUPREMOS FRFET<sup>®</sup> MOSFET's optimized body diode reverse recovery performance can remove additional component and improve system reliability.

### Features

- $650 \text{ V} @ \text{T}_{\text{J}} = 150^{\circ}\text{C}$
- Typ.  $R_{DS(on)} = 57.5 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q<sub>g</sub> = 240 nC)
- Low Effective Output Capacitance (Typ. Coss(eff.) = 420 pF)
- 100% Avalanche Tested
- This Device is Pb-Free and is RoHS Compliant

### Applications

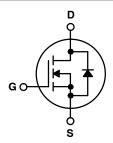
- Solar Inverter
- AC-DC Power Supply



## **ON Semiconductor®**

## www.onsemi.com

V <sub>DS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX		
600 V	65 mΩ @ 10 V	48.5 A		

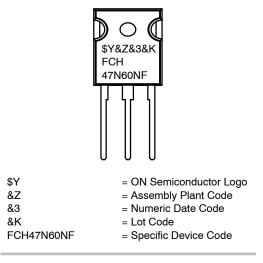


N-CHANNEL MOSFET



TO-247-3LD CASE 340CK

### MARKING DIAGRAM



## **ORDERING INFORMATION**

See detailed ordering and shipping information on page 2 of this data sheet.

Unit V V А

А mJ А mJ V/ns

W W/°C °C °C

MOSFET	<b>MAXIMUM RATINGS</b> ( $T_C = 25^{\circ}C$ unless	ess otherwise noted)		
Symbol		Parameter	FCH47N60NF	
V <sub>DSS</sub>	Drain to Source Voltage		600	
$V_{GSS}$	Gate to Source Voltage		±30	
Ι <sub>D</sub>	Drain Current	– Continuous (T <sub>C</sub> = 25°C)	45.8	
		– Continuous (T <sub>C</sub> = 100°C)	28.9	
I <sub>DM</sub>	Drain Current	– Pulsed (Note 1)	137.4	
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note	2)	2926	
I <sub>AR</sub>	Avalanche Current (Note 1)		15.3	
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		3.7	
dv/dt	MOSFET dv/dt		100	
	Peak Diode Recovery dv/dt (Note 3)		50	
PD	Power Dissipation	(T <sub>C</sub> = 25°C)	368	
		– Derate above 25°C	2.94	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		–55 to + 150	
ΤL	Maximum Lead Temperature for Solder	ing, 1/8" from Case for 5 Second	300	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Repetitive Rating: Pulse width limited by maximum junction temperature. 2.  $I_{AS} = 15.3 \text{ A}$ ,  $R_G = 25 \Omega$ , starting  $T_J = 25 \text{ °C}$ 3.  $I_{SD} \le 45.8 \text{ A}$ , di/dt  $\le 1200 \text{ A/}\mu\text{s}$ ,  $V_{DD} \le 380 \text{ V}$ , starting  $T_J = 25 \text{ °C}$ 

## **THERMAL CHARACTERISTICS**

Symbol	Parameter	FCH47N60NF	Unit
$R_{ ext{ heta}JC}$	Thermal Resistance, Junction to Case, Max.	0.34	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	

#### PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Mark	Package	Package Method	Reel Size	Tape Width	Quantity
FCH47N60NF	FCH47N60NF	TO-247-3LD	Tube	N/A	N/A	30 Units

## **ELECTRICAL CHARACTERISTICS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
OFF CHARA	ACTERISTICS	·				
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}, T_C = 25^{\circ}\text{C}$	600	-	-	V
$\Delta BV_{DSS}$ / $\Delta T_{J}$	Breakdown Voltage Temperature Coefficient	$I_D = 1 \text{ mA}$ , Referenced to 25°C	-	0.78	_	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 480 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	-	-	10	μΑ
		$V_{DS}$ = 480 V, $V_{GS}$ = 0 V, $T_{C}$ = 125 $^{\circ}C$	-	-	100	
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS}$ = $\pm 30$ V, $V_{DS}$ = 0 V	-	-	±100	nA
ON CHARA	CTERISTICS					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS}=V_{DS},\ I_{D}=250\ \mu A$	3	-	5	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 23.5 \text{ A}$	-	57.5	65.0	mΩ
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 40 \text{ V}, \text{ I}_{D} = 23.5 \text{ A}$	-	52	100	S
DYNAMIC C	HARACTERISTICS					
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V,	-	4600	6120	pF
C <sub>oss</sub>	Output Capacitance	f = 1 MHz	-	195	260	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1	-	3.0	5.0	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS}$ = 380 V, $V_{GS}$ = 0 V, f = 1 MHz	-	108	-	pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	$V_{DS}$ = 0 V to 380 V, $V_{GS}$ = 0 V	-	492	-	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10 V	$V_{DS} = 380 \text{ V}, \text{ I}_{D} = 23.5 \text{ A},$	-	121	157	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	V <sub>GS</sub> = 10 V (Note 4)	-	23	-	nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge		-	47	-	nC
ESR	Equivalent Series Resistance (G-S)	f = 1 MHz	-	0.9	-	Ω
SWITCHING	CHARACTERISTICS					
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = 380 \text{ V}, \text{ I}_{D} = 23.5 \text{ A},$	-	34	78	ns
t <sub>r</sub>	Turn–On Rise Time	R <sub>G</sub> = 4.7 Ω (Note 4)	-	22	54	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		-	117	244	ns
t <sub>f</sub>	Turn-Off Fall Time		-	4	18	ns
DRAIN-SOU	IRCE DIODE CHARACTERISTICS					
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	47	А
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	141	Α
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, \text{ I}_{SD} = 23.5 \text{ A}$	-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 V, I_{SD} = 23.5 A,$	-	169	_	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dl <sub>F</sub> /dt = 100 A/μs	-	1.3	_	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Essentially Independent of Operating Temperature Typical Characteristics.

## **TYPICAL CHARACTERISTICS**

500

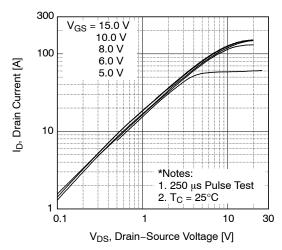


Figure 1. On-Region Characteristics

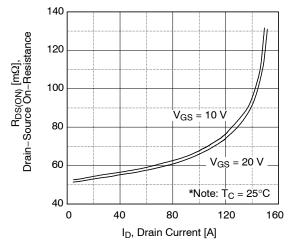
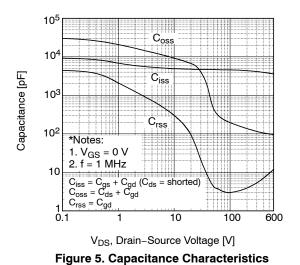
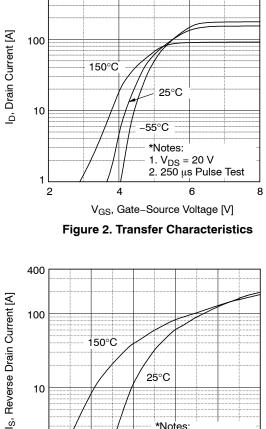


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage





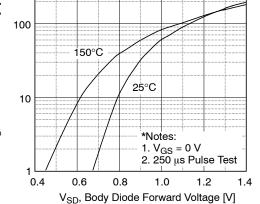
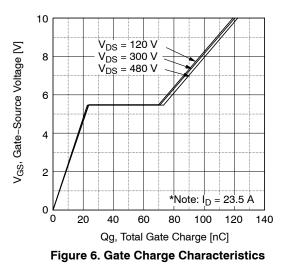
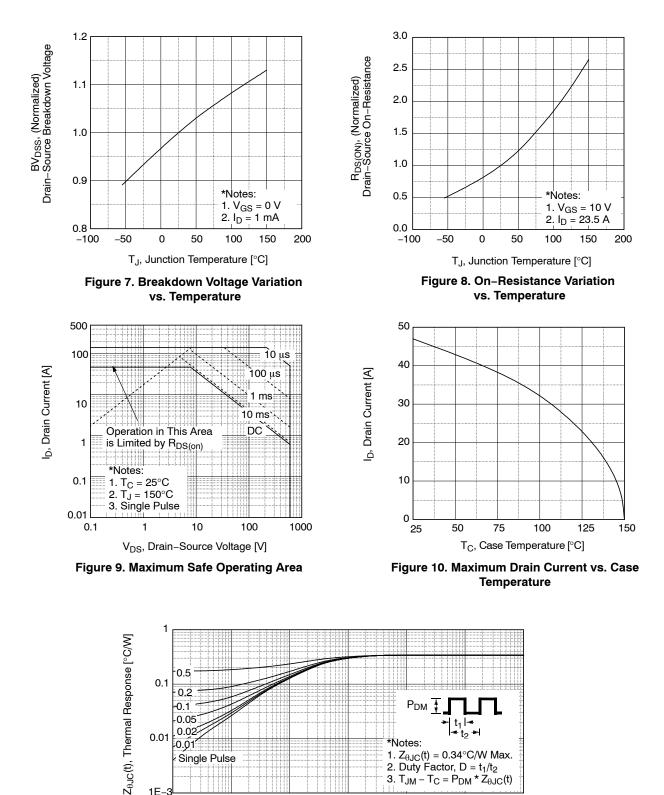


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature



## TYPICAL CHARACTERISTICS (continued)



10-2

t1, Rectangular Pulse Duration [sec] Figure 11. Transient Thermal Response Curve

10–<sup>3</sup>

0.01

10-5

1E-

Single Pulse

10-4

\*Notes:

 $10^{-1}$ 

1.  $Z_{\theta JC}(t) = 0.34^{\circ}C/W$  Max. 2. Duty Factor, D =  $t_1/t_2$ 

3.  $T_{JM} - T_C = P_{DM} * Z_{\theta JC}(t)$ 

10<sup>0</sup>

10<sup>1</sup>

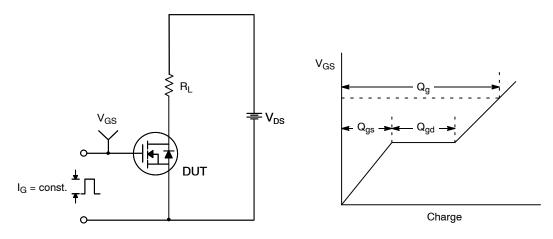


Figure 12. Gate Charge Test Circuit & Waveform

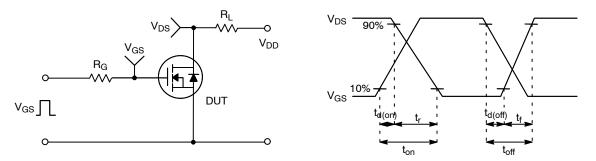


Figure 13. Resistive Switching Test Circuit & Waveforms

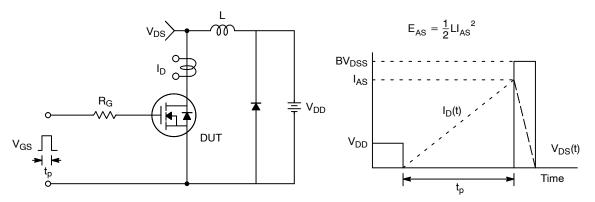


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

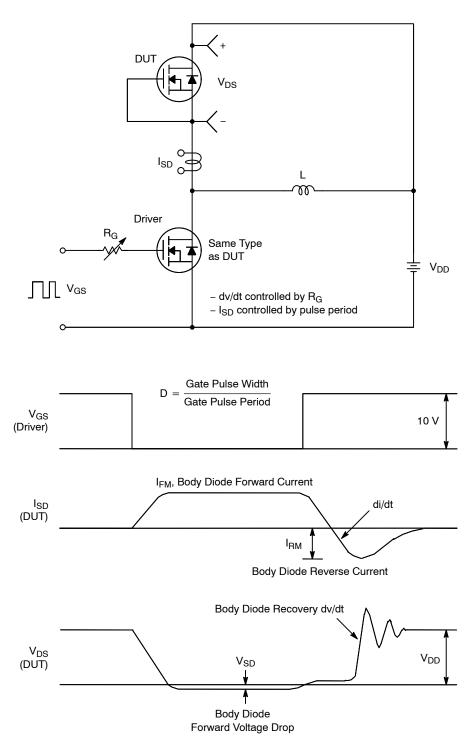


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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